

HIGH EFFICIENCY CHARGE PUMP FOR 7 WLEDs WITH I²C INTERFACE

FEATURES

- 3.0-V to 6.0-V Input Voltage Range
- ×1 and ×1.5 Charge Pump
- Fully Programmable Current with I²C
 - 64 Dimming Steps with 25mA Maximum (Sub and Main Display Banks)
 - 4 Dimming Steps with 80mA Maximum (DM5 for Auxiliary Application)
- 2% Current Matching for Sub LEDs at Light Load Condition (Each 100μA)
- 750-kHz Charge Pump Frequency
- Continuous 230-mA Maximum Output Current
- Auto Switching Between ×1 and ×1.5 Mode for Maximum Efficiency
- Built-in Soft Start and Current Limit
- Open Lamp Detection
- 16-Pin 3mm x 3mm QFN

APPLICATIONS

- Cellular Phones
- PDA, PMP, GPS (Up To 4 Inch LCD Display)
- Multidisplay Handheld Devices

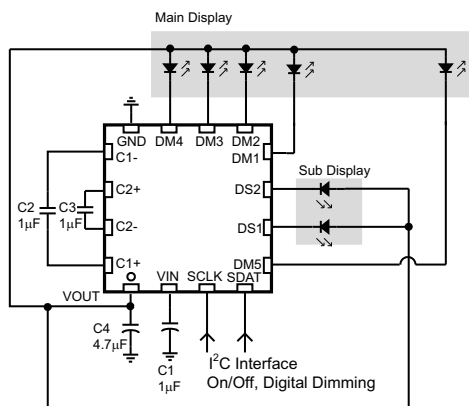


Figure 1. Typical Application for Sub and Main

DESCRIPTION

The TPS60250 is a high efficiency, constant frequency charge pump DC/DC converter that uses a dual mode 1× and 1.5× conversion to maximize efficiency over the input voltage range. It drives up to five white LEDs for a main display and up to two white LEDs for a sub display with regulated constant current for uniform intensity. By utilizing adaptive 1×/1.5× charge pump modes and very low-dropout current regulators, the TPS60250 achieves high efficiency over the full 1-cell lithium-battery input voltage range.

Four enable inputs, ENmain, ENsub1, ENsub2, and ENaux, available through I²C, are used for simple on/off controls for the independent main, sub1, sub2, and DM5 displays, respectively. To lower operating current when using one sub display LED, the device provides completely separate operation in sub display LEDs.

The TPS60250 is available in a 16-pin 3mmx3mm thin QFN.

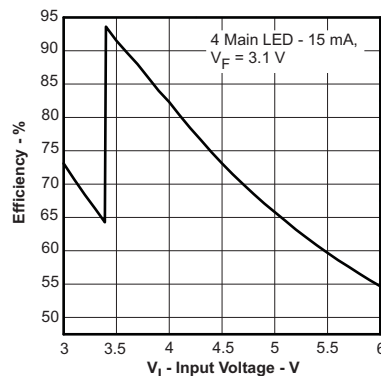


Figure 2. Efficiency vs Input Voltage

ORDERING INFORMATION⁽¹⁾

PART NUMBER	PACKAGE	T _A
TPS60250RTE	16 Pin 3 mm × 3 mm QFN (RTE)	–40°C to +85°C

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		VALUE	UNIT
V _I	Input voltage range (all pins)	–0.3 to 7	V
	MAX Output current limit	650	mA
	HBM ESD Rating ⁽²⁾	2	kV
	CDM ESD Rating ⁽³⁾	500	V
	MM ESD Rating ⁽⁴⁾	200	V
T _A	Operating temperature range	–40 to 85	°C
T _J	Maximum operating junction temperature	150	°C
T _{ST}	Storage temperature	–55 to 150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The Human body model (HBM) is a 100-pF capacitor discharged through a 1.5-kΩ resistor into each pin. The testing is done according JEDECs EIA/JESD22-A114.
- (3) Charged Device Model
- (4) Machine Model (MM) is a 200-pF capacitor discharged through a 500-nH inductor with no series resistor into each pin. The testing is done according JEDECs EIA/JESD22-A115.

DISSIPATION RATINGS

PACKAGE	THERMAL RESISTANCE, R _{θJC}	THERMAL RESISTANCE, R _{θJA}	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 85°C POWER RATING
QFN 3×3 RTE	74.6°C/W	48.7°C/W	2.05 W	1.13 W	0.821 W

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
V _I	Input voltage range	3.0		6.0	V
I _{O(max)}	Maximum output current		230		mA
C _I	Input capacitor		1.0		μF
C _O	Output capacitor		4.7		μF
C ₁ , C ₂	Flying capacitor		1.0		μF
T _A	Operating ambient temperature	–40		85	°C
T _J	Operating junction temperature	–40		125	°C

ELECTRICAL CHARACTERISTICS

V_I = 3.5 V, T_A = –40°C to 85°C, typical values are at T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY VOLTAGE					
V _I	Input voltage range	3.0		6.0	V
I _Q	Operating quiescent current			6.7	mA
	750-kHz Switching in 1.5× Mode (I _{MAIN_LED} = 15 mA × 4, I _O = 60 mA)				
	No switching in ×1 mode (I _O = 100 μA)			68	μA
I _{SD}	Shutdown current			1.3	μA
V _{UVLO1}	UVLO Threshold voltage1 ⁽¹⁾	2.2	2.4	2.6	V
V _{UVLO2}	UVLO Threshold voltage2 ⁽²⁾	1.2	1.3	1.5	V

- (1) Shut down charge pump and power stage and keep I²C content
- (2) Shut down completely and come up with all 0's after device restart

ELECTRICAL CHARACTERISTICS (continued)

$V_I = 3.5\text{ V}$, $T_A = -40^\circ\text{C}$ to 85°C , typical values are at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{hys}	Under-voltage lockout hysteresis	UVLO1		210		mV
T _S	Soft start time ⁽³⁾	V _I = 3 V, C _O = 1 μF, I _{MAIN_LED} = 15 mA × 4		0.5		ms
CHARGE PUMP						
V _{out}	Overvoltage limit			6.5		V
F _s	Switching frequency			750		kHz
R _O	Open loop output impedance	×1 Mode, (V _I – V _O)/I _O			1.2	Ω
		× 1.5 Mode, (V _I × 1.5 – V _O)/I _O V _I = 3.0V (I _O = 120mA)		3.5	5.0	
CURRENT SINK						
K _{m_sub}	Current matching of sub LEDs at light load condition ⁽⁴⁾	I _{SUB_LED} = 100 μA × 2, V _{DXX} = 0.4 V		0	±2%	
K _{m_main}	LED to LED Current matching ⁽⁵⁾	I _{MAIN_LED} = 15 mA × 4, 3.0 V ≤ V _I ≤ 4.2 V		±1%	±5%	
K _a	Current accuracy	I _{LED} = 15 mA			±7%	
I _{D_MS}	Maximum LED current of DM1-4 and DS1-2	Main and Sub Display Current Register = 0×01&2(111111), V _{DXX} = 0.2 V		25.5		mA
I _{D_DM5}	Maximum LED current of DM5	Aux Display Current Register = 0×03 (XXXX11), V _{DM5} = 0.4 V		80		mA
V _{DropOut}	LED Drop out voltage	See ⁽⁶⁾		80	120	mV
V _{TH_GU}	1× Mode to 1.5× mode transition threshold voltage ⁽⁷⁾	V _{DXX} Falling, 15 mA × 4 measured on the lowest V _{DXX}	85	100	120	mV
V _{TH_GD}	Input voltage hysteresis for 1.5× to 1× mode transition	Measured as V _I – (V _O – V _{DXX_MIN}), I _{MAIN_LED} = 15 mA × 4		470		mV
SERIAL INTERFACE TIMING REQUIREMENTS						
f _{max}	Clock frequency				400	kHz
t _{WH(HIGH)}	Pulse duration, clock high time			600		ns
t _{WL(LOW)}	Pulse duration, clock low time			1300		ns
t _r	DATA and CLK rise time				300	ns
t _f	DATA and CLK fall time				300	ns
t _{h(STA)}	High time (repeated) START condition(after this period the first clock pulse is generated)			600		ns
t _{su(STA)}	Setup time for repeated START condition			600		ns
t _{h(DATA)}	Data input hold time			0		ns
t _{su(DATA)}	Data input setup time			100		ns
t _{su(STO)}	STOP condition setup time			600		ns
t _(BUF)	Bus free time			1300		ns
I ² C COMPATIBLE INTERFACE VOLTAGE SPECIFICATION (SCLK, SDAT, VIO)						
V _{IL}	Low-level input voltage	3.0V ≤ V _I ≤ 6.0V	0		0.5	V
V _{IH}	High-level input voltage	3.0V ≤ V _I ≤ 6.0V	1.1			V
V _{OL}	Low-level output voltage	I _{LOAD} = 2 mA			0.4	V

(3) Measurement Condition: From enabling the LED driver to 90% output voltage after V_I is already up.

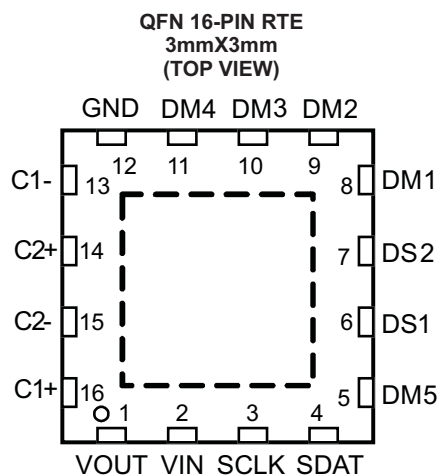
(4) LED current matching is defined as: $(I_{\text{SUB_LED_WORST}} - I_{\text{AVG_SUB}}) / I_{\text{AVG_SUB}}$

(5) LED to LED Current Matching is defined as: $(I_{\text{MAIN_LED_WORST}} - I_{\text{AVG_MAIN}}) / I_{\text{AVG_MAIN}}$

(6) Dropout Voltage is defined as V_{DXX} (WLED Cathode) to GND voltage at which current into the LED drops 10% from the LED current at $V_{\text{DXX}} = 0.2\text{ V}$, WLED current = $15\text{ mA} \times 4$.

(7) As V_I drops, V_{DXX} eventually falls below the switchover threshold of 100mV, and TPS60250 switches to $1.5 \times$ mode. See the *Operating Principle* section for details about the mode transition thresholds.

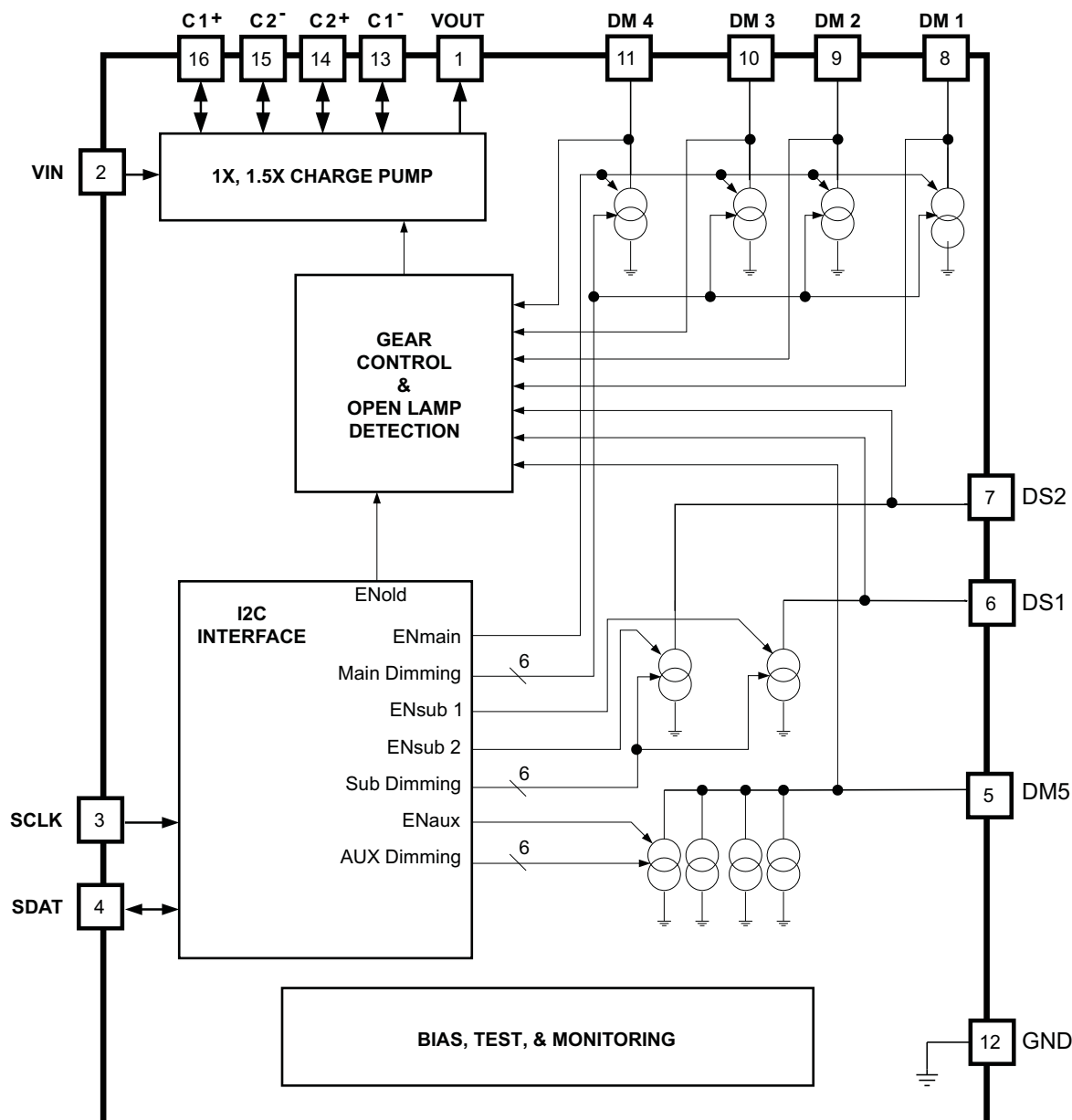
PIN ASSIGNMENTS



TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
VOUT	1	O	Connect the anodes of the sub, main, and aux display white LEDs to this pin. Bypass decouple VOUT to GND with a 4.7- μ F or greater ceramic capacitor.
VIN	2	I	Supply voltage input. Connect to a 3-V to 6-V input supply source. Bypass VIN to GND with a 1- μ F or greater ceramic capacitor.
SCLK	3	I	I ² C Interface
SDAT	4	I/O	I ² C Interface
DM5	5	I	Current sink input. Connect the cathode of the aux display or the 5th main display white LED to this pin.
DS1	6	I	Current sink input. Connect the cathode of one of the sub display white LEDs to this pin.
DS2	7	I	
DM1	8	I	Current sink input. Connect the cathode of one of the main display white LED to this pin.
DM2	9	I	
DM3	10	I	
DM4	11	I	
GND	12	–	Ground
C1–	13	–	Connect to the flying capacitor C1
C2+	14	–	Connect to the flying capacitor C2
C2–	15	–	Connect to the flying capacitor C2
C1+	16	–	Connect to the flying capacitor C1

FUNCTIONAL BLOCK DIAGRAM



TYPICAL CHARACTERISTICS

TABLE OF GRAPHS

DESCRIPTION		REF
Efficiency	Efficiency vs Input Voltage, 4 Main LED - 15mA, 25mA	Figure 3
	Efficiency vs Input Voltage, 2 Sub LED with Light Load Condition, $\times 1$ Mode Operation	Figure 4
Output Impedance of $\times 1$ and $\times 1.5$ Mode	Switch Resistance vs Free-Air Temperature, $\times 1$ Mode, $I_{LED} = 230$ mA	Figure 5
	Switch Resistance vs Free-Air Temperature, $\times 1$ Mode, $I_{LED} = 100$ mA	Figure 6
	Switch Resistance vs Free-Air Temperature, $\times 1.5$ Mode Charge Pump Open-Loop, $I_{LED} = 230$ mA	Figure 7
	Switch Resistance vs Free-Air Temperature, $\times 1.5$ Mode Charge Pump Open-Loop, $I_{LED} = 100$ mA	Figure 8
Shutdown Current	Shutdown Current vs Input Voltage	Figure 9
Input Current	Input Current vs Supply Voltage, 4 Main LED	Figure 10

TYPICAL CHARACTERISTICS (continued)

DESCRIPTION		REF
DM5 with Maximum 80 mA	DM5 Current vs Input Voltage, Programmed with 80 mA	Figure 11
Current Accuracy	WLED Current vs Input Voltage, 4 Main LED with 15 mA	Figure 12

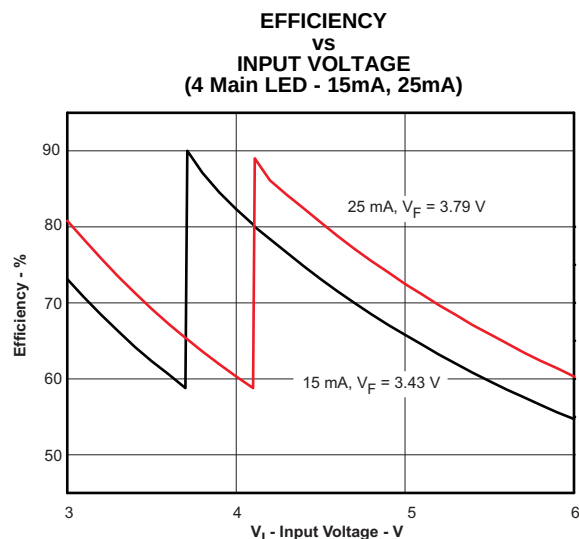


Figure 3.

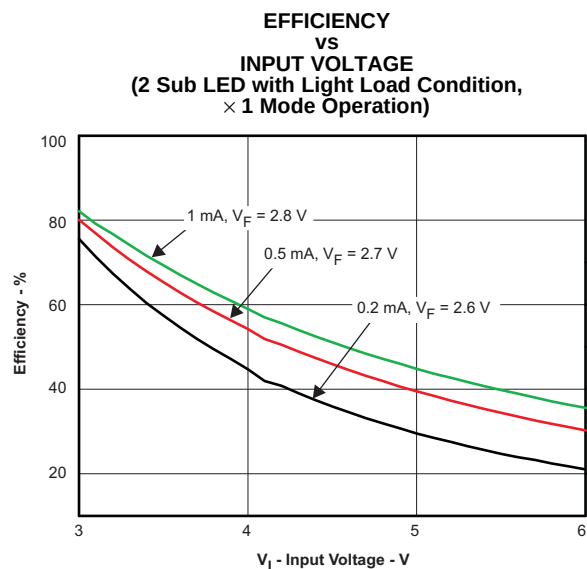


Figure 4.

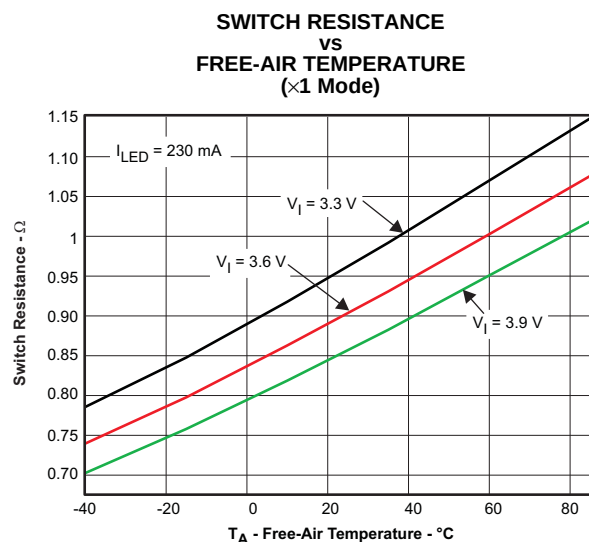


Figure 5.

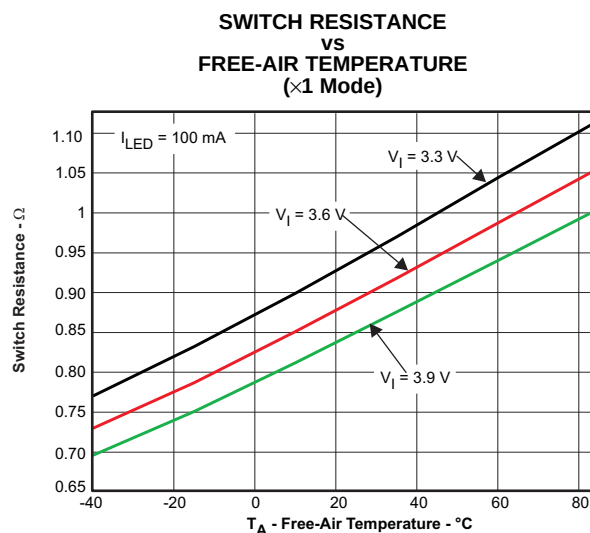


Figure 6.

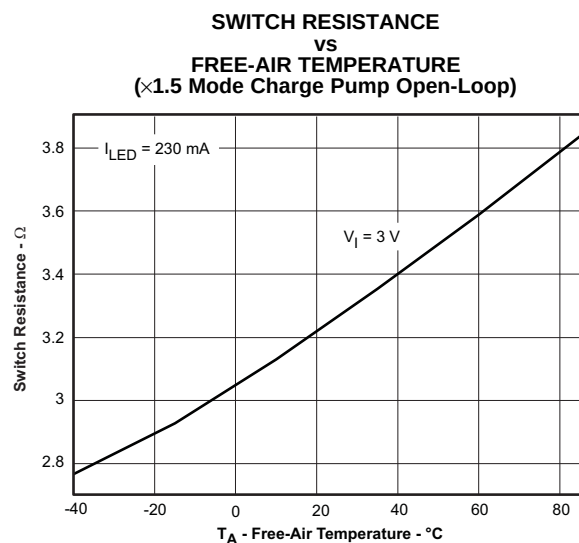


Figure 7.

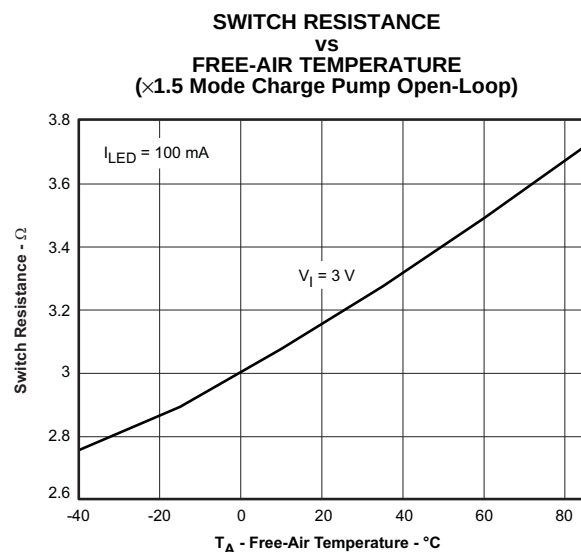


Figure 8.

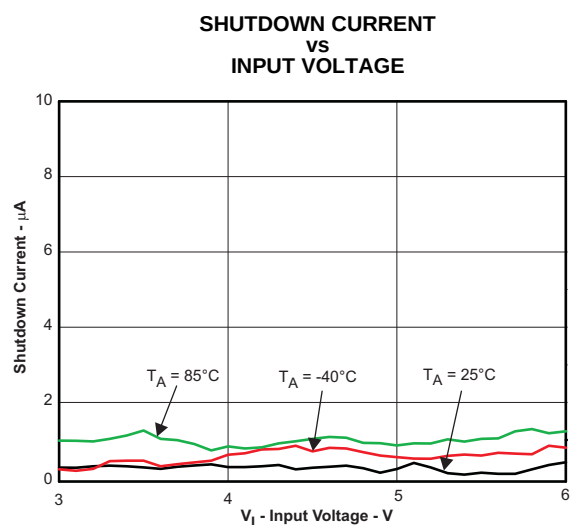


Figure 9.

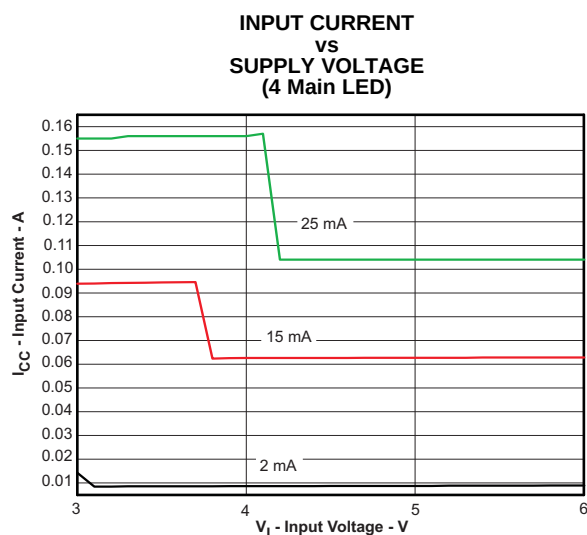
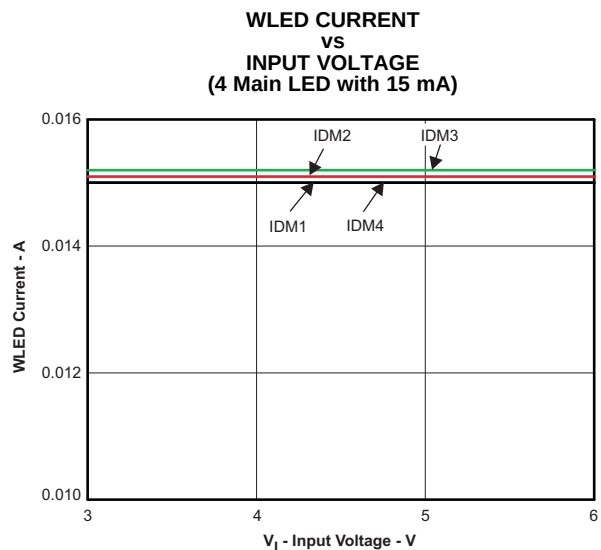
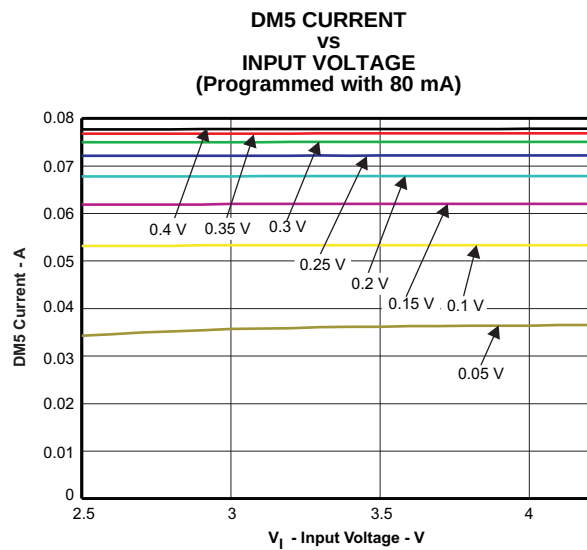


Figure 10.



APPLICATION INFORMATION

APPLICATION OVERVIEW

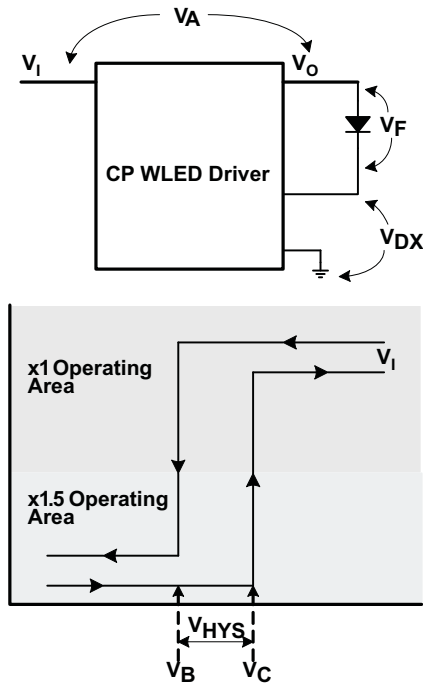
Most of the current handsets fall into one of three categories. First is the clamshell design, with a main display on the inside, a secondary display on the outside and a keypad backlight. Second is the bar design, with a main display and a keypad backlight. Third is the slide type (slide-up and slide-down) design, with a main display and two keypad banks (inside and outside). The TPS60250 is well suited for use in these three major phone designs because it has 7 individually regulated white LED current paths and that drive up to five white LEDs in main display and up to two white LEDs in sub display with regulated constant current for uniform intensity. The main and sub display LED channels drive up to 25mA and an auxiliary LED output (DM5) drives up to 80mA that can be assigned for keypad backlight, torch light or low cost/weak camera flash application using I²C interface.

The TPS60250 circuit uses only 4 external components: the input/output capacitors and 2 chargepump flying capacitors. The few external components combined with the small 3mm×3mm QFN package provide for a small total solution size. By combining independent control of three separate banks of backlight LEDs with low cost and weak flash capability, the TPS60250 helps designers minimize power consumption especially in case of light load condition while reducing component count and package size.

OPERATING PRINCIPLE

Charge pumps are becoming increasingly attractive in battery-operated applications where board space and maximum height of the converter are critical constraints. The major advantage of a charge pump is the use of only capacitors as storage elements. The TPS60250 chargepump provides regulated LED current from a 3-V to 6-V input source. It operates in two modes. The 1× mode, where the input is connected to the output through a pass element, and a high efficiency 1.5× charge pump mode. The IC maximizes power efficiency by operating in 1× and 1.5× modes as input voltage and LED current conditions require. The mode of operation is automatically selected by comparing the forward voltage of the WLED plus the voltage of current sink for each LED with the input voltage. The IC starts up in 1× mode, and automatically transitions to 1.5× if the voltage at any current sink input (DM_{_} or DS_{_}) falls below the 100-mV transition voltage. The IC returns to 1× mode as the input rises. [Figure 13](#) provides a visual explanation of the 1× to 1.5× transition.

In 1.5× mode, the internal oscillator determines the charge/discharge cycles for the flying capacitors. During a charge cycle, the flying capacitors are connected in series and charged up to the input voltage. After the on-time of the internal oscillator expires, the flying capacitors are reconfigured to be in parallel and then connected in series to the input voltage. This provides an output of 1.5× the input voltage. After the off-time of the internal oscillator expires, another charge cycle initiates and the process repeats.

APPLICATION INFORMATION (continued)**Figure 13. Input Voltage Hysteresis Between ×1 and ×1.5 Mode**

As shown in Figure 13, there is input voltage hysteresis voltage between 1× and 1.5× mode to ensure stable operation during mode transition. For the 1 cell Li-Ion battery input voltage range, the TPS60250 operates in 1× mode when a fully charged battery is installed. Once the battery voltage drops below the V_B level, which is the mode transition voltage from 1× to 1.5×, the WLED driver operates in 1.5× mode. Once in 1.5× mode, the battery voltage must rise to the V_C level in order to transition from 1.5× to 1×. This hysteresis ensures stable operation when there is some input voltage fluctuation at the 1×/1.5× mode transition. The WLED driver provides a typical 280mV hysteresis voltage (V_{HYS}) that changes based on LED current, to prevent oscillating between modes.

The transition voltage, V_B , depends on V_{DX} (the mode transition threshold voltage), V_F (WLED forward voltage drop) and V_A (the drop out voltage of the charge pump stage) and is calculated as follows:

$$V_B = V_A + V_F + V_{DX}$$

$$V_A = R_{OUT1X} \times I_{LEDTOTAL}$$

Where R_{OUT1X} is the 1× mode output impedance of the IC. See the Electrical Characteristics table for output impedance specifications.

The TPS60250 switches up to 1.5× mode when the input voltage is below V_B and remains in 1.5× mode as long as the input is lower than V_C . 1.5× Mode is exited when the input voltage rises above V_C . V_C is calculated as:

$$V_C = V_F + 470 \text{ mV}$$

The input voltage mode transition hysteresis voltage (V_{HYS}) between 1× and 1.5× is calculated using the following equation.

$$V_{HYS} = V_C - V_B = 520 \text{ mV} - V_{DX} - V_A, \text{ where } V_{DX} = 100\text{mV}$$

Note that V_A is the key factor in determining V_{HYS} and is dependant on the 1× mode charge pump output impedance and WLED current.

APPLICATION INFORMATION (continued)

LED CURRENT SINKS (DM_, DS_)

The TPS60250 has constant current sinks which drive seven individual LED current paths. Each current sink regulates the LED current to a constant value determined by the I²C interface. The internal register addressing allows the LED main channels DM1~DM5 to be controlled independently from the LED sub channels DS1~DS2. All the LED channels sink up to 25mA of current except DM5 which has an 80-mA maximum current when configured as an auxiliary output. Using the I²C interface, the user may assign DM5 to the main display bank with up to 25-mA current or as an auxiliary output for torch or keypad light or low/weak camera flash with 80-mA current. DM5 has 64 dimming steps same as main and sub display banks when assigned to the main display. However, it has its own current programming register and enable control. When assigned as an auxiliary, DM5 has 4 dimming steps (full scale, 70%, 40%, 20%).

These optimized current sinks minimize the voltage headroom required to drive each LED and maximize power efficiency by increasing the amount of time the controller stays in 1× mode before transitioning to 1.5× mode.

OPEN LAMP DETECTION

In system production it is often necessary to leave LED current paths open depending on the phone model. For example, one phone may use 2 LEDs to backlight the main display while another uses 4 LEDs. Rather than use two different ICs for these different phone applications, the TPS60250 may be used in both applications with no additional efficiency loss in the 2 LED applications. In traditional LED driver applications when an LED current path is open, the current sink voltage falls to ground and the current regulation circuitry drives the output to a maximum voltage in an attempt to regulate the current for the missing LED path. This severely reduces the system efficiency. The TPS60250 uses 7 internal comparators to detect when one or more open LED condition occurs and shut down prevent it from forcing the device to gear up the open current sink. The open lamp detection is enabled/disabled using the I²C interface.

CAPACITOR SELECTION

The TPS60250 is optimized to work with ceramic capacitors with a dielectric of X5R or better. The two flying capacitors must be the same value for proper operation. The 750-kHz switching frequency requires that the flying capacitor be less than 4.7μF. Use of 1-μF ceramic capacitors for both chargepump flying capacitors is recommended.

For good input voltage filtering, low ESR ceramic capacitors are recommended. A 1-μF ceramic input capacitor is sufficient for most of the applications. For better input voltage filtering this value can be increased.

The output capacitor controls the amount of ripple on the output. Since small ripple is undetectable by the human eye, a 4.7-μF output capacitor works well. If better output filtering and lower ripple is desired, a larger output capacitor may be used.

SETTING THE LED CURRENT

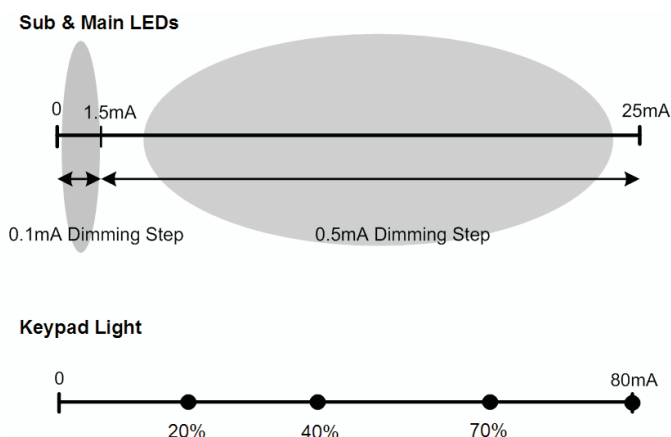


Figure 14. Dimming Steps for Sub, Main, and Keypad Backlight

APPLICATION INFORMATION (continued)

Figure 14 shows the dimming steps for sub, main, and auxiliary display banks in the 25mA maximum current application. In order to satisfy today's requirement on LED current, the TPS60250 covers low LED current area from 100 μ A to 1.5mA with 100- μ A dimming step (total 16 steps for 25-mA maximum current) for the new LCD panels which have improved transparency rates. For LED currents in the range from 2mA to 25mA, the device uses 48 dimming steps with 0.5mA step. Also, DM5 has 4 dimming steps once the current path is assigned for auxiliary applications with maximum 80-mA current.

SERIAL INTERFACE

The serial interface is compatible with the standard and fast mode I²C specifications, allowing transfers at up to 400 kHz. The interface adds flexibility to the WLED driver solution, enabling most functions to be programmed to new values depending on the instantaneous application requirements. Register contents remain intact as long as V_{CC} remains above UVLO2 (typical 1.3V).

For normal data transfer, DATA is allowed to change only when CLK is low. Changes when CLK is high are reserved for indicating the start and stop conditions. During data transfer, the data line must remain stable whenever the clock line is high. There is one clock pulse per bit of data. Each data transfer is initiated with a start condition and terminated with a stop condition. When addressed, the TPS60250 device generates an acknowledge bit after the reception of each byte. The master device (microprocessor) must generate an extra clock pulse that is associated with the acknowledge bit. The TPS60250 device must pull down the DATA line during the acknowledge clock pulse so that the DATA line is a stable low during the high period of the acknowledge clock pulse. Setup and hold times must be taken into account. During read operations, a master must signal the end of data to the slave by not generating an acknowledge bit on the last byte that was clocked out of the slave. In this case, the slave TPS60250 device must leave the data line high to enable the master to generate the stop condition.

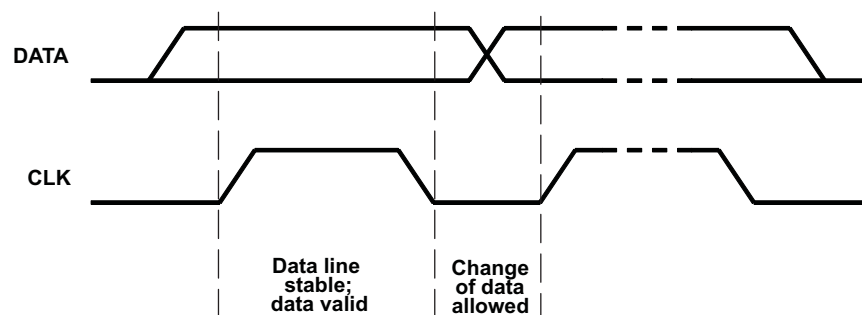


Figure 15. Bit Transfer on the Serial Interface

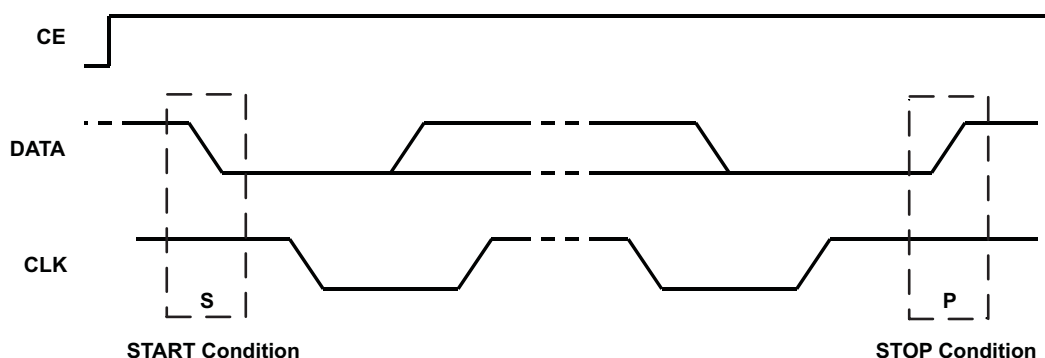


Figure 16. START and STOP Conditions

APPLICATION INFORMATION (continued)

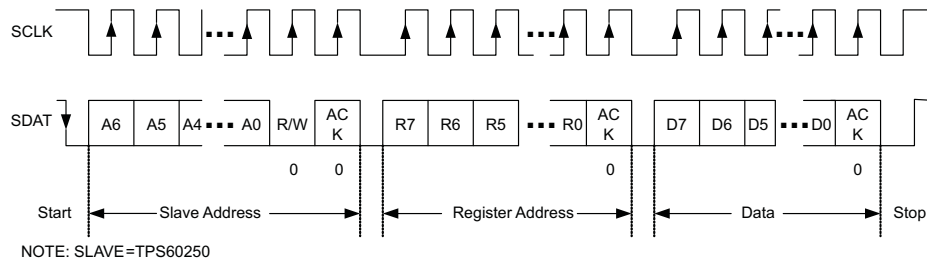


Figure 17. Serial I/F READ From TPS60250: Protocol A

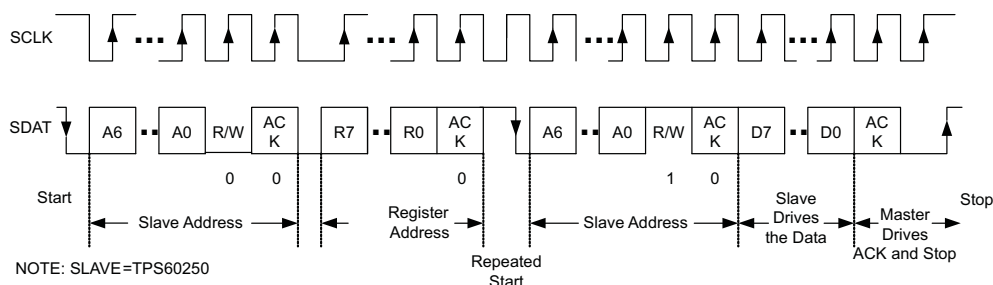


Figure 18. Serial I/F READ From TPS60250: Protocol B

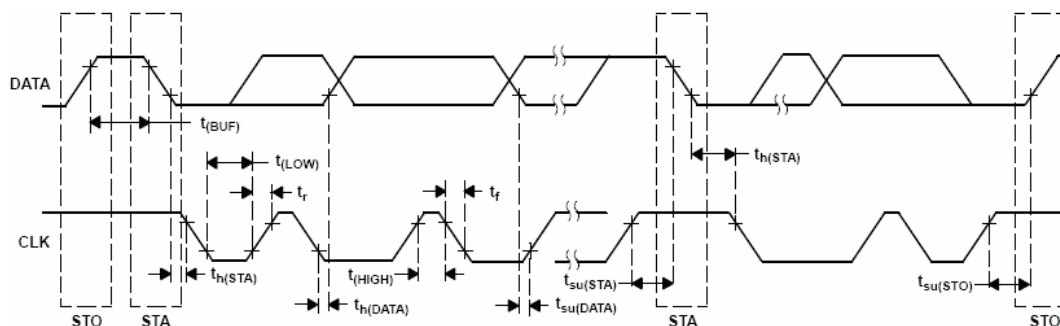


Figure 19. Serial I/F Timing Diagram

The I²C interface uses a combined protocol in which the START condition and the Slave Address are both repeated. The TPS60250 provides 2 I²C Slave Address using internal EEPROM in case more than 1 device is used in the system. The primary I²C Slave Address is **1110111**. For alternative I²C address, contact the factory.

APPLICATION INFORMATION (continued)**Enable Control Register (Address: 0x00h)**

ENABLE	B7	B6	B5	B4	B3	B2	B1	B0
BIT NAME	X	ENold	ENmain	ENsub2	ENsub1	ENaux	DM5H	DM5L

- Bit 6 ENold (Enable Open Lamp Detection)
1: Open Lamp Detection Enabled
0: Open Lamp Detection Disabled
- Bit 5 ENmain
1: Enable Main Display LEDs (DM1-DM4)
0: Disable Main Display LEDs
- Bit 4 ENsub2
1: Enable Sub Display LED 2 (DS2)
0: Disable Sub Display LED 2
- Bit 3 ENsub1
1: Enable Sub Display LED 1 (DS1)
0: Disable Sub Display LED 1
- Bit 2 ENaux
1: Enable Aux Display LED (DM5)
0: Disable Aux Display LED
- Bits 1,0 DM5H, DM5L

DM5H (B1)	DM5L (B0)	DM5 Mode and Shutdown Mode
0	0	Shutdown mode. All outputs disabled, all internal registers set to 0x00h
0	1	Enable the IC and Group DM5 as main display with maximum current of 25mA
1	0	Enable the IC and set DM5 as Aux output with maximum current of 80mA. Dimming steps determined by laux0 and laux1 bits.
1	1	Shutdown mode. All outputs disabled, all internal registers set to 0x00h

Sub Display Current Control Register (Address: 0x01h)

SUB DISP CURRENT	B7	B6	B5	B4	B3	B2	B1	B0
BIT NAME	X	X	lsub5	lsub4	lsub3	lsub2	lsub1	lsub0

- Bits 5 - 0 lsub5 - lsub0 (total 64 steps)
6-Bit command (64 steps) to these bits sets the current for DS1 and DS2.
For LED currents between 0 and 1.5mA, one step = 0.1mA increment
For LED currents between 1.5 and 25.5mA, one step = 0.5mA increment

Main Display Current Control Register (Address: 0x02h)

MAIN DISP CURRENT	B7	B6	B5	B4	B3	B2	B1	B0
BIT NAME	X	X	lmain5	lmain4	lmain3	lmain2	lmain1	lmain0

- Bits 5 - 0 lmain5 - lmain0 (total 64 steps)
6-Bit command (64 steps) to these bits sets the current for DM1-DM4.
For LED currents between 0 and 1.5mA, one step = 0.1mA increment
For LED currents between 1.5 and 25.5mA, one step = 0.5mA increment

Aux Output Brightness and Operation Mode Control Register (Address: 0x03h)

AUX DISP CURRENT	B7	B6	B5	B4	B3	B2	B1	B0
BIT NAME	laux5	laux4	laux3	laux2	laux1	laux0	Mode1	Mode0

Bits 7 - 2 (DM5 set to Main Display Mode)

laux5 - laux0 (total 64 steps)

6-Bit command (64 steps) to these bits sets the current for DM5.

For LED currents between 0 and 1.5mA, one step = 0.1mA increment

For LED currents between 1.5 and 25.5mA, one step = 0.5mA increment

Bits 7 - 2 (DM5 set to Aux Display Mode)

laux5 (B7)	laux4 (B6)	laux3 (B5)	laux2 (B4)	laux1 (B3)	laux0 (B2)	Aux Dimming Step
X	X	X	X	0	0	20%
X	X	X	X	0	1	40%
X	X	X	X	1	0	70%
X	X	X	X	1	1	100%

Bits 1,0 Mode1, Mode0

Mode1 (B1)	Mode0 (B0)	TPS60250 Mode
0	0	Auto-Switchover Mode. The TPS60250 selects 1×/1.5× mode as described in the <i>Operating Principle</i> section.
0	1	1× Mode. TPS60250 remains in 1× mode regardless of the input voltage. LED current may not regulate at lower input voltages when in this mode.
1	0	1.5× Mode. TPS60250 remains in 1.5× mode regardless of the input voltage.
1	1	Auto-Switchover Mode. The TPS60250 selects 1×/1.5× mode as described in the <i>Operating Principle</i> section.

APPLICATION CIRCUITS

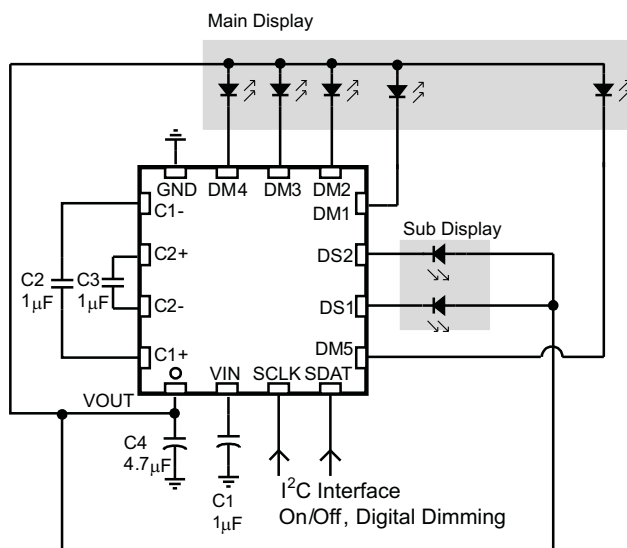


Figure 20. The Typical Application Circuit for Sub and Main Display

As shown in [Figure 20](#), this is a typical application circuit for a clam shell phone with 5 main LEDs and 2 sub LEDs. Recently, the LCD panel makers have developed a new panel that has improved the transparency rate which makes the system efficiency with a 100-µA LED current a critical load point. To meet system efficiency requirements with the light load conditions for the new LCD operating panel, the TPS60250 has a maximum 55-µA operating current with the 100-µA output load condition. In this application, the controller always operates in 1× mode due to the WLED's low forward voltage drop (about 2.6V_F with a 100-µA WLED current). Thus, the total efficiency at a light load condition is determined using [Equation 1](#):

$$\eta_{\text{Light}} = \frac{I_O \times V_F}{V_{\text{in}} \times (I_O + I_{\text{op}})} \quad (1)$$

Where:

- I_O: Output Load (WLED) Current
- V_F: Forward Voltage Drop of WLED
- V_{in}: Input Voltage
- I_{op}: Operating Current of LED Driver

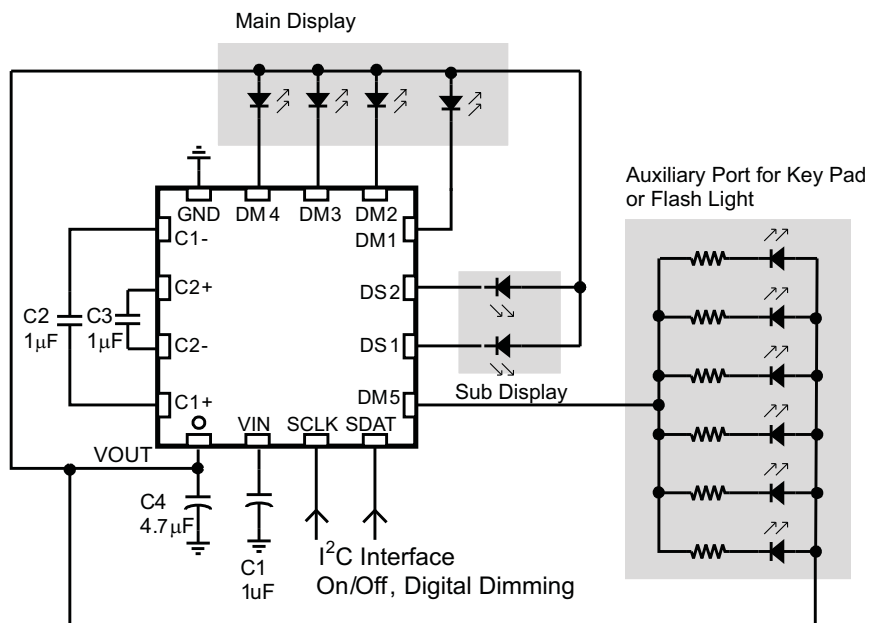


Figure 21. The Typical Application Circuit for Sub, Main, and Keypad Backlight

Figure 21 shows the typical application circuit for sub, main, and keypad backlight. In this application, DM5 is assigned as the auxiliary input for the keypad lighting application.

LAYOUT GUIDELINES

There are several points to consider when laying out a PCB for charge pump based solutions. In general, all capacitors should be as close as possible to the device. This is especially important when placing the flying capacitors (C2, C3 in Figure 20 and Figure 21). In cases where DM5 is assigned for torch/flash applications, with a maximum 80-mA WLED current, this current path must be kept wide to reduce the trace resistance.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS60250RTER	ACTIVE	QFN	RTE	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60250RTET	ACTIVE	QFN	RTE	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

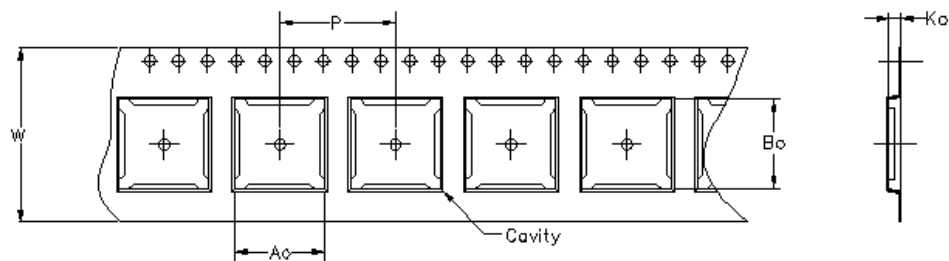
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

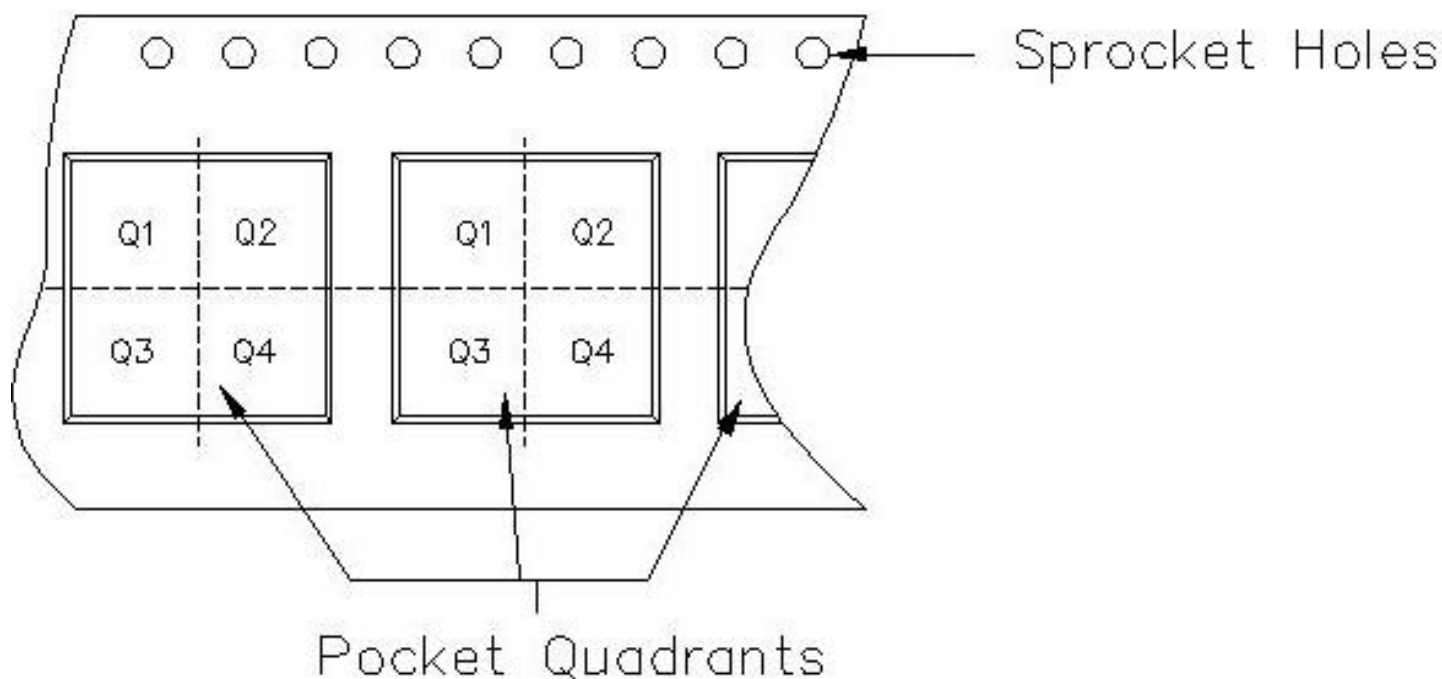
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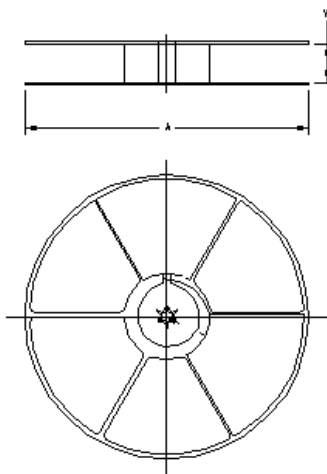
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



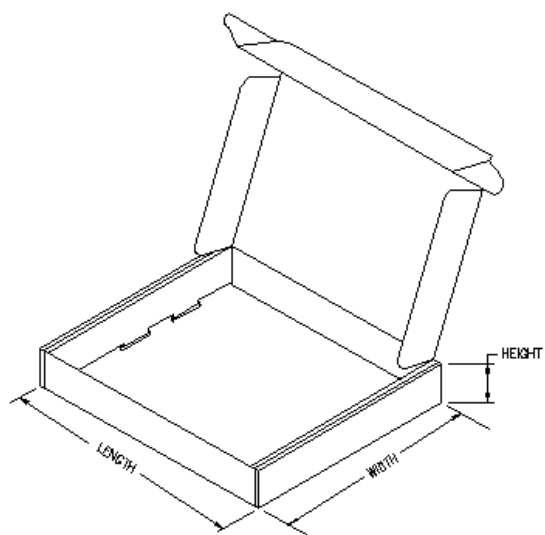
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60250RTER	RTE	16	MLA	330	12	3.3	3.3	1.1	8	12	PKGORN T2TR-MS P
TPS60250RTET	RTE	16	MLA	177	12	3.3	3.3	1.1	8	12	PKGORN T2TR-MS P



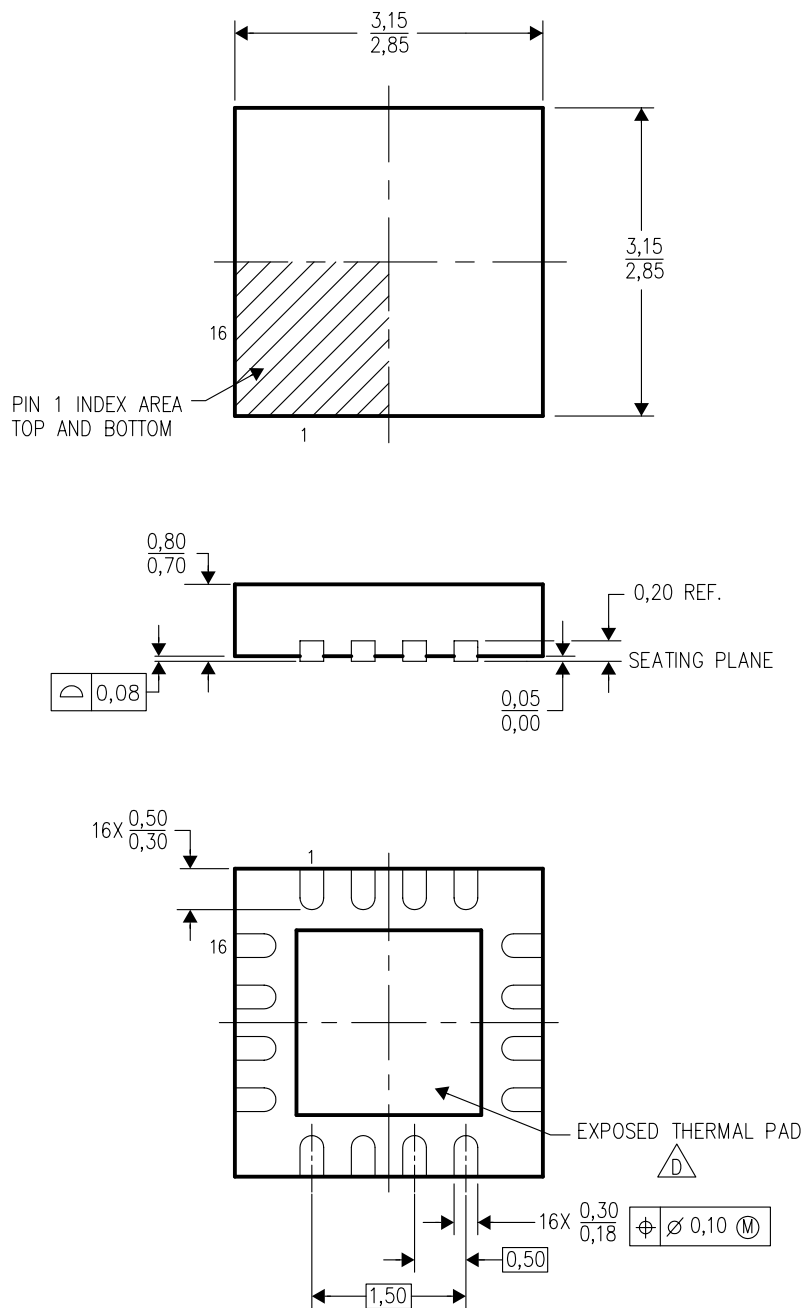
TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
TPS60250RTER	RTE	16	MLA	342.9	336.6	28.58
TPS60250RTET	RTE	16	MLA	190.0	212.7	31.75



RTE (S-PQFP-N16)

PLASTIC QUAD FLATPACK



4205254/B 11/04

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Quad Flatpack, No-leads (QFN) package configuration.

 The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.

E. Falls within JEDEC MO-220.

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